

JUN 16 2004

SHEET 1 OF 26

**INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)**

ATTY. DOCKET NO.  
007733 USA/FPS/MMCS/APC

SERIAL NO.  
10/765,921

APPLICANT  
Alexander T. SCHWARM

FILING DATE  
January 29, 2004

GROUP

**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
SS	5,642,296	06/24/97	Saxena			07/29/93
	5,646,870	07/08/97	Krivokapic et al.			02/13/95
	5,719,796	02/17/98	Chen			12/04/95
	5,787,269	07/28/98	Hyodo			09/19/95
	5,859,964	01/12/99	Wang et al.			10/25/96
	5,960,185	09/28/99	Nguyen			06/24/96
	6,210,983 B1	04/03/01	Atchison et al.			06/15/99
	6,360,184 B1	03/19/02	Jacquez			03/26/97
	6,397,114 B1	05/28/02	Eryurek et al.			05/03/99

**FOREIGN PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation
	WO 01/25865 A1	04/12/01	WO			X

**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

	Chang, Norman H. and Costas J. Spanos. February 1991. "Continuous Equipment Diagnosis Using Evidence Integration: An LPCVD Application." <i>IEEE Transactions on Semiconductor Manufacturing</i> , v. 4, n. 1, pp. 43-51.
	Boning, Duane S., Jerry Stefani, and Stephanie W. Butler. February 1999. "Statistical Methods for Semiconductor Manufacturing." <i>Encyclopedia of Electrical Engineering</i> , J. G. Webster, Ed.
	"Semiconductor Manufacturing: An Overview." < <a href="http://users.ece.gatech.edu/~gmay/overview.html">http://users.ece.gatech.edu/~gmay/overview.html</a> >

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↓	3,205,485	09/07/65	Noltingk	5,4		10/21/60
	3,229,198	01/11/66	Libby	9,1		09/28/62
	3,767,900	10/23/73	Chao et al.	7,9		06/23/71
	3,920,965	11/18/75	Sohrwardy	0,9		03/04/74
	4,000,458	12/28/76	Miller et al.	0,4		08/21/75
	4,207,520	06/10/80	Flora et al.	7,5		04/06/78
	4,209,744	06/24/80	Gerasimov et al.	9,7		03/27/78
	4,302,721	11/24/81	Urbanek et al.	2,7		05/15/79
	4,368,510	01/11/83	Anderson	3,5		10/20/80
	4,609,870	09/02/86	Lale et al.	9,8		09/13/84
	4,616,308	10/07/86	Morshedi et al.	5,31		12/02/85
	4,663,703	05/05/87	Axelby et al.	3,71		10/02/85
	4,698,766	10/06/87	Entwistle et al.	3,71		05/17/85
	4,750,141	06/07/88	Judell et al.	3,11		11/26/85
	4,755,753	07/05/88	Chern	5,72		07/23/86
	4,757,259	07/12/88	Charpentier	7,22		11/05/86
	4,796,194	01/03/89	Atherton	5,15		08/20/86
	4,901,218	02/13/90	Cornwell	1,2		03/04/88
	4,938,600	07/03/90	Into	1,61		02/09/89
	4,967,381	10/30/90	Lane et al.	7,31		07/06/89
	5,089,970	02/18/92	Lee et al.	9,9		10/05/89
↓	5,108,570	04/28/92	Wang	1,51		03/30/90
	5,208,765	05/04/93	Turnbull	1,71		07/20/90
	5,220,517	06/15/93	Sierk et al.	1,5		08/31/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
↓	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
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<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
↓	5,270,222	12/14/93	Moslehi			12/31/90	
	5,283,141	02/01/94	Yoon et al.			03/05/92	
	5,295,242	03/15/94	Mashruwala et al.			11/02/90	
	5,309,221	05/03/94	Fischer et al.			12/31/91	
	5,329,463	07/12/94	Sierk et al.			01/13/93	
	5,338,630	08/16/94	Yoon et al.			11/18/93	
	5,347,446	09/13/94	Iino et al.			02/10/92	
	5,367,624	11/22/94	Cooper			06/11/93	
	5,375,064	12/20/94	Bollinger			12/02/93	
	5,398,336	03/14/95	Tantry et al.			06/16/93	
	5,402,367	03/28/95	Sullivan et al.			07/19/93	
	5,408,405	04/18/95	Mozumder et al.			09/20/93	
	5,410,473	04/25/95	Kaneko et al.			12/16/92	
	5,420,796	05/30/95	Weling et al.			12/23/93	
	5,427,878	06/27/95	Corliss			07/16/94	
	5,469,361	11/21/95	Moyne			06/03/94	
	5,485,082	01/16/96	Wisspeintner et al.			04/05/90	
	5,490,097	02/06/96	Swenson et al.			08/06/93	
	5,495,417	02/27/96	Fuduka et al.			03/16/93	
	5,497,316	03/05/96	Sierk et al.			04/04/95	
	5,497,381	03/05/96	O'Donoghue et al.			06/01/95	
	5,503,707	04/02/96	Maung et al.			09/22/93	
	5,508,947	04/16/96	Sierk et al.			05/13/94	
	5,511,005	04/23/96	Abbe et al.			02/16/94	
	5,519,605	05/21/96	Cawfield			10/24/94	
5,525,808	06/11/96	Irie et al.			12/20/94		
5,526,293	06/11/96	Mozumder et al.			12/17/93		
5,534,289	07/09/96	Bilder et al.			01/03/95		
5,541,510	07/30/96	Danielson			04/06/95		
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	5,546,312	08/13/96	Mozumder et al.			02/24/94			
	5,553,195	09/03/96	Meijer			09/29/94			
	5,586,039	12/17/96	Hirsch et al.			02/27/95			
	5,599,423	02/04/97	Parker et al.			06/30/95			
	5,602,492	02/11/97	Cresswell et al.			04/28/94			
	5,603,707	02/18/97	Trombetta et al.			11/28/95			
	5,617,023	04/01/97	Skalski			02/02/95			
	5,627,083	05/06/97	Tounai			05/12/95			
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96			
	5,649,169	07/15/97	Berezin et al.			06/20/95			
	5,654,903	08/05/97	Reitman et al.			11/07/95			
	5,655,951	08/12/97	Meikle et al.			09/29/95			
	5,657,254	08/12/97	Sierk et al.			04/15/96			
	5,661,669	08/26/97	Mozumder et al.			06/07/95			
	5,663,797	09/02/97	Sandhu			05/16/96			
	5,664,987	09/09/97	Renteln			09/04/96			
	5,665,199	09/09/97	Sahota et al.			06/23/95			
	5,666,297	09/09/97	Britt et al.			05/13/94			
	5,667,424	09/16/97	Pan			09/25/96			
	5,674,787	10/07/97	Zhao et al.			01/16/96			
	5,694,325	12/02/97	Fukuda et al.			11/22/95			
	5,698,989	12/16/97	Nulman			09/13/96			
	5,719,495	02/17/98	Moslehi			06/05/96			
	5,735,055	04/07/98	Hochbein et al.			04/23/96			
5,740,429	04/14/98	Wang et al.			07/07/95				
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	5,751,582	05/12/98	Saxena et al.		05	09/24/96	
	5,754,297	05/19/98	Nulman		05	04/14/97	
	5,761,064	06/02/98	La et al.		06	10/06/95	
	5,761,065	06/02/98	Kittler et al.		06	03/30/95	
	5,764,543	06/09/98	Kennedy		05	06/16/95	
	5,777,901	07/07/98	Berezin et al.		07	09/29/95	
	5,787,021	07/28/98	Samaha		07	12/18/95	
	5,808,303	09/15/98	Schlagheck et al.		09	01/29/97	
	5,812,407	09/22/98	Sato et al.		09	08/12/97	
	5,823,854	10/20/98	Chen		10	05/28/96	
	5,825,913	10/20/98	Rostami et al.		10	07/18/95	
	5,828,778	10/27/98	Hagi et al.		10	07/12/96	
	5,832,224	11/03/98	Fehskens et al.		11	06/14/96	
	5,838,595	11/17/98	Sullivan et al.		11	11/25/96	
	5,844,554	12/01/98	Geller et al.		12	09/17/96	
	5,857,258	01/12/99	Penzes et al.		01	05/12/94	
	5,858,975	01/12/99	Brewer et al.		01	08/09/96	
	5,862,054	01/19/99	Li		01	02/20/97	
	5,863,807	01/26/99	Jang et al.		01	03/15/96	
	5,867,389	02/02/99	Hamada et al.		02	11/26/96	
	5,870,306	02/09/99	Harada		02	06/13/97	
	5,883,437	03/16/99	Maruyama et al.		03	12/28/95	
	5,889,991	03/30/99	Consolatti et al.		03	12/06/96	
	5,901,313	05/04/99	Wolfe et al.		05	09/02/97	
5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96		
5,910,011	06/08/99	Cruse			05/12/97		
5,910,846	06/08/99	Sandhu			08/19/97		
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	5,912,678	06/15/99	Saxena et al.		134	04/14/97
	5,916,016	06/29/99	Bothra		294	10/23/97
	5,923,553	07/13/99	Yi		134	10/05/96
	5,926,690	07/20/99	Toprac et al.		104	05/28/97
	5,930,138	07/27/99	Lin et al.		174	09/10/97
	5,940,300	08/17/99	Ozaki		174	05/08/97
	5,943,237	08/24/99	Van Boxem		144	10/17/97
	5,960,214	09/28/99	Sharpe, Jr. et al.		184	12/04/96
	5,961,369	10/05/99	Bartels et al.		154	06/04/98
	5,963,881	10/05/99	Kahn et al.		154	10/20/97
	5,978,751	11/02/99	Pence et al.		29	02/25/97
	5,982,920	11/09/99	Tobin, Jr. et al.		94	01/08/97
	6,002,989	12/14/99	Shiba et al.		44	04/01/97
	6,017,771	01/25/00	Yang et al.		54	04/27/98
	6,036,349	03/14/00	Gombar		44	07/26/96
	6,041,263	03/21/00	Boston et al.		14	10/01/97
	6,041,270	03/21/00	Steffan et al.		14	12/05/97
	6,054,379	04/25/00	Yau et al.		54	02/11/98
	6,064,759	05/16/00	Buckley et al.		64	11/06/97
	6,072,313	06/06/00	Li et al.		54	06/17/97
	6,074,443	06/13/00	Venkatesh et al.		34	01/29/98
	6,077,412	06/20/00	Ting et al.		34	10/30/98
	6,078,845	06/20/00	Friedman		14	11/25/96
	6,094,688	07/25/00	Mellen-Garnett et al.		1	03/12/98
	6,097,887	08/01/00	Hardikar et al.			10/27/97
	6,108,092	08/22/00	Sandhu			06/08/99
	6,111,634	08/29/00	Pecen et al.			05/28/97
	6,112,130	08/29/00	Fukuda et al.			10/01/97
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	6,127,263	10/03/00	Parikh		137	07/10/98
	6,128,016	10/03/00	Coelho et al.		137	12/20/96
	6,136,163	10/24/00	Cheung et al.		147	03/05/99
	6,141,660	10/31/00	Bach et al.		117	07/16/98
	6,143,646	11/07/00	Wetzel		177	06/03/97
	6,148,099	11/14/00	Lee et al.		47	07/03/97
	6,148,239	11/14/00	Funk et al.		47	12/12/97
	6,148,246	11/14/00	Kawazome		47	06/10/98
	6,150,664	11/21/00	Su		117	06/29/99
	6,159,075	12/12/00	Zhang		27	10/13/99
	6,159,644	12/12/00	Satoh et al.		27	03/06/96
	6,161,054 B1	12/12/00	Rosenthal et al.		27	09/17/98
	6,169,931 B1	01/02/01	Runnels		27	07/29/98
	6,172,756 B1	01/09/01	Chalmers et al.		27	12/11/98
	6,173,240 B1	01/09/01	Sepulveda et al.		197	11/02/98
	6,175,777 B1	01/16/01	Kim		57	01/16/98
	6,178,390 B1	01/23/01	Jun		37	09/08/98
	6,183,345 B1	02/06/01	Kamono et al.		57	03/20/98
	6,185,324 B1	02/06/01	Ishihara et al.		57	01/31/95
	6,191,864 B1	02/20/01	Sandhu		57	02/29/00
	6,192,291 B1	02/20/01	Kwon		07	10/08/98
	6,197,604 B1	03/06/01	Miller et al.		57	10/01/98
	6,204,165 B1	03/20/01	Ghoshal		57	06/24/99
	6,211,094 B1	04/03/01	Jun et al.		77	08/23/99
	6,214,734 B1	04/10/01	Bothra et al.			11/20/98
	6,217,412 B1	04/17/01	Campbell et al.			08/11/99
	6,219,711 B1	04/17/01	Chari			10/01/97
	6,222,936 B1	04/24/01	Phan et al.			09/13/99
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	6,226,792 B1	05/01/01	Goiffon et al.		C	10/14/98			
	6,230,069 B1	05/08/01	Campbell et al.		C	06/26/98			
	6,236,903 B1	05/22/01	Kim et al.		C	09/25/98			
	2001/0001755 A1	05/24/01	Sandhu et al.		C	12/29/00			
	6,240,330 B1	05/29/01	Kurtzberg et al.		C	05/28/97			
	6,240,331 B1	05/29/01	Yun		C	08/18/98			
	2001/0003084 A1	06/07/01	Finarov		C	12/04/00			
	6,245,581 B1	06/12/01	Bonser et al.		C	04/19/00			
	6,246,972 B1	06/12/01	Klimasauskas		C	05/27/99			
	6,248,602 B1	06/19/01	Bode et al.		C	11/01/99			
	6,249,712 B1	06/19/01	Boiquaye		C	09/25/96			
	6,252,412 B1	06/26/01	Talbot et al.		C	01/08/99			
	6,253,366 B1	06/26/01	Mutschler, III		C	03/31/99			
	6,263,255 B1	07/17/01	Tan et al.		C	05/18/98			
	6,271,670 B1	08/07/01	Caffey		C	02/08/99			
	6,276,989 B1	08/21/01	Campbell et al.		C	08/11/99			
	6,278,899 B1	08/21/01	Piche et al.		C	10/06/98			
	6,280,289 B1	08/28/01	Wiswesser et al.		C	11/02/98			
	6,284,622 B1	09/04/01	Campbell et al.		C	10/25/99			
	6,287,879 B1	09/11/01	Gonzales et al.		C	08/11/99			
	6,290,572 B1	09/18/01	Hofmann		C	03/23/00			
	6,292,708 B1	09/18/01	Allen et al.		C	06/11/98			
	6,298,274 B1	10/02/01	Inoue		C	09/01/99			
	6,298,470 B1	10/02/01	Breiner et al.		C	04/15/99			
	6,303,395 B1	10/16/01	Nulman		C	06/01/99			
	6,304,999 B1	10/16/01	Toprac et al.		C	10/23/00			
	2001/0030366 A1	10/18/01	Nakano et al.		C	03/07/01			
	6,307,628 B1	10/23/01	Lu et al.		C	08/18/00			
	6,314,379 B1	11/06/01	Hu et al.		C	12/04/97			
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	2001/0039462 A1	11/08/01	Mendez et al.			04/02/01	
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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>				<b>ATTY. DOCKET NO.</b> 007733 USA/FPS/MMCS/APC		<b>SERIAL NO.</b> 10/765,921			
				<b>APPLICANT</b> Alexander T. SCHWARM					
				<b>FILING DATE</b> January 29, 2004				<b>GROUP</b>	
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	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
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	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
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		10/759,108	01/20/04	Schwarm	Automated Design and Execution of Experiments with Integrated Model Creation for Semiconductor Manufacturing Tools		
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						Yes	No
	61-66104 ✓	04/04/86	Japan			X	pa.
	61-171147	08/01/86	Japan			X	par
	01-283934	11/15/89	Japan			X	par
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	2,050,247 ✓	08/29/91	Canada			X	ana
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	05-266029 ✓	10/15/93	Japan			X	par
	06-110894	04/22/94	Japan			X	par
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	06-184434 ✓	07/05/94	Japan			X	par
	06-252236 ✓	09/09/94	Japan			X	pa
	06-260380 ✓	09/16/94	Japan			X	par
	EP 0 621 522 A2 ✓	10/26/94	Europe			X	roy
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	08-50161 ✓	02/20/96	Japan			X	par
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	08-304023	11/22/96	Japan			X	pa
	EP 0 747 795 A2 ✓	12/11/96	Europe			X	roy
	09-34535 ✓	02/07/97	Japan			X	par
	9-246547	09/19/97	Japan			X	
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						Yes	No
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	EP 0 895 145 A1	02/03/99	Europe			X	ope
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	11-126816	05/11/99	Japan			X	in
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	WO 99/25520	05/27/99	WO			X	
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	WO 00/00874	01/06/00	WO			X	
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	WO 00/35063	06/15/00	WO			X	
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	WO 00/54325	09/14/00	WO			X	
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	WO 00/79355 A1	12/28/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	ope
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	WO 01/11679 A1	02/15/01	WO			X	
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		<b>FILING DATE</b> January 29, 2004	<b>GROUP</b>
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**INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)**



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10/765,921

APPLICANT  
Alexander T. SCHWARM

FILING DATE  
January 29, 2004

GROUP  
2125

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				APPLICANT Alexander T. SCHWARM			
				FILING DATE January 29, 2004		GROUP 2125	
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				FILING DATE January 29, 2004		GROUP 2125	
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(PTO-1449)

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**SERIAL NO.**  
**10/765.921**

**APPLICANT**  
**Alexander T. SCHWARM**

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**January 29, 2004**

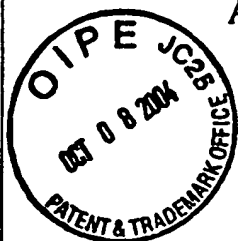
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**GROUP  
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